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September 1983 Revised May 2005

# MM74HC273 Octal D-Type Flip-Flops with Clear

### **General Description**

The MM74HC273 edge triggered flip-flops utilize advanced silicon-gate CMOS technology to implement D-type flip-flops. They possess high noise immunity, low power, and speeds comparable to low power Schottky TTL circuits. This device contains 8 master-slave flip-flops with a common clock and common clear. Data on the D input having the specified setup and hold times is transferred to the Q output on the LOW-to-HIGH transition of the CLOCK input. The CLEAR input when LOW, sets all outputs to a low state

Each output can drive 10 low power Schottky TTL equivalent loads. The MM74HC273 is functionally as well as pin compatible to the 74LS273. All inputs are protected from damage due to static discharge by diodes to  $V_{\mbox{\footnotesize CC}}$  and ground.

### **Features**

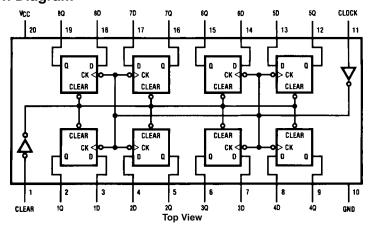
- Typical propagation delay: 18 ns
- Wide operating voltage range
- Low input current: 1 µA maximum
- Low quiescent current: 80 µA (74 Series)
- Output drive: 10 LS-TTL loads

### **Ordering Code:**

Order Number	Package Number	Package Description
MM74HC273WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
MM74HC273SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC273MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC273N	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

### **Connection Diagram**



### **Truth Table**

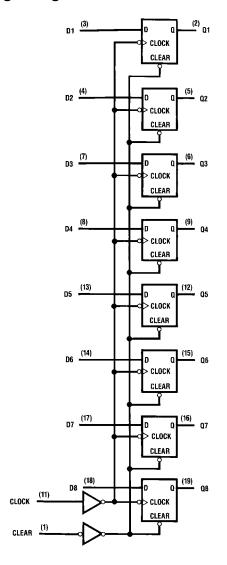
(Each Flip-Flop)

pop)			
	Inputs		Outputs
Clear	Clock	D	Q
L	Х	Х	L
Н	<b>↑</b>	Н	Н
Н	1	L	L
Н	L	X	$Q_0$

- H = HIGH Level (Steady State)
  L = LOW Level (Steady State)
  X = Don't Care

  ↑ = Transition from LOW-to-HIGH level
  Q<sub>0</sub> = The level of Q before the indicated steady state input conditions were established

### **Logic Diagram**



# Absolute Maximum Ratings(Note 1) (Note 2)

 $\begin{array}{lll} \text{DC Output Voltage (V_{OUT})} & -0.5 \text{ to V}_{CC} + 0.5 \text{V} \\ \text{Clamp Diode Current (I}_{IK}, I_{OK}) & \pm 20 \text{ mA} \\ \text{DC Output Current, per pin (I}_{OUT}) & \pm 25 \text{ mA} \\ \text{DC V}_{CC} \text{ or GND Current, per pin (I}_{CC}) & \pm 50 \text{ mA} \\ \text{Storage Temperature Range (T}_{STG}) & -65^{\circ}\text{C to} + 150^{\circ}\text{C} \\ \end{array}$ 

Power Dissipation ( $P_D$ )

(Note 3) 600 mW S.O. Package only 500 mW

Lead Temperature (T<sub>L</sub>)

(Soldering 10 seconds) 260°C

# Recommended Operating Conditions

	Min	Max	Units
Supply Voltage (V <sub>CC</sub> )	2	6	V
DC Input or Output Voltage			
$(V_{IN}, V_{OUT})$	0	$V_{CC}$	V
Operating Temperature Range (T <sub>A</sub> )	-40	+85	°C
Input Rise or Fall Times			
$(t_r, t_f) V_{CC} = 2.0V$		1000	ns
V <sub>CC</sub> = 4.5V		500	ns
$V_{CC} = 6.0V$		400	ns

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature denating — plastic "N" package:

Note 3: Power Dissipation temperature derating — plastic "N" package: – 12 mW/°C from 65°C to 85°C.

### DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	V <sub>CC</sub>	T <sub>A</sub> = 25°C		T <sub>A</sub> = -40 to 85°C	T <sub>A</sub> = -55 to 125°C	Units
Зушьог			VCC	Тур		Guaranteed L		
V <sub>IH</sub>	Minimum HIGH Level		2.0V		1.5	1.5	1.5	V
	Input Voltage		4.5V		3.15	3.15	3.15	V
			6.0V		4.2	4.2	4.2	V
V <sub>IL</sub>	Maximum LOW Level		2.0V		0.5	0.5	0.5	V
	Input Voltage		4.5V		1.35	1.35	1.35	V
			6.0V		1.8	1.8	1.8	V
V <sub>OH</sub>	Minimum HIGH Level	$V_{IN} = V_{IH}$ or $V_{IL}$						
	Output Voltage	$ I_{OUT}  \le 20 \ \mu A$	2.0V	2.0	1.9	1.9	1.9	V
			4.5V	4.5	4.4	4.4	4.4	V
			6.0V	6.0	5.9	5.9	5.9	V
		$V_{IN} = V_{IH}$ or $V_{IL}$						
		$ I_{OUT}  \le 4.0 \text{ mA}$	4.5V	4.2	3.98	3.84	3.7	V
		$ I_{OUT}  \le 5.2 \text{ mA}$	6.0V	5.7	5.48	5.34	5.2	V
V <sub>OL</sub>	Maximum LOW Level	$V_{IN} = V_{IH}$ or $V_{IL}$						
	Output Voltage	$ I_{OUT}  \le 20 \ \mu A$	2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	V
			6.0V	0	0.1	0.1	0.1	V
		$V_{IN} = V_{IH}$ or $V_{IL}$						
		$ I_{OUT}  \le 4 \text{ mA}$	4.5V	0.2	0.26	0.33	0.4	V
		$ I_{OUT}  \le 5.2 \text{ mA}$	6.0V	0.2	0.26	0.33	0.4	V
I <sub>IN</sub>	Maximum Input	V <sub>IN</sub> = V <sub>CC</sub> or GND	6.0V		±0.1	±1.0	±1.0	μА
	Current							
I <sub>CC</sub>	Maximum Quiescent	V <sub>IN</sub> = V <sub>CC</sub> or GND	6.0V		8	80	160	μА
	Supply Current	I <sub>OUT</sub> = 0 μA						

Note 4: For a power supply of 5V  $\pm$ 10% the worst case output voltages ( $V_{OH}$ , and  $V_{OL}$ ) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case  $V_{IH}$  and  $V_{IL}$  occur at  $V_{CC} = 5.5V$  and 4.5V respectively. (The  $V_{IH}$  value at 5.5V is 3.85V.) The worst case leakage current ( $I_{IN}$ ,  $I_{CC}$ , and  $I_{OZ}$ ) occur for CMOS at the higher voltage and so the 6.0V values should be used.

### **AC Electrical Characteristics**

 $V_{CC} = 5V$ ,  $T_A = 25^{\circ}C$ ,  $C_L = 15$  pF,  $t_r = t_f = 6$  ns

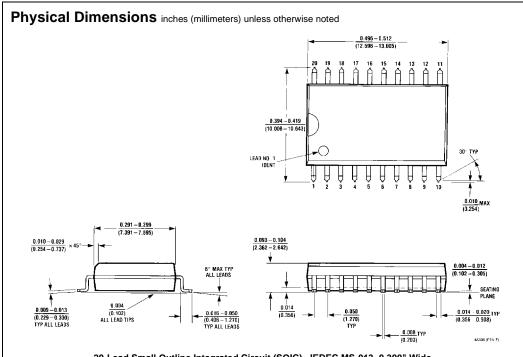
Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Units
f <sub>MAX</sub>	Maximum Operating Frequency		50	30	MHz
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation		18	27	ns
	Delay, Clock to Output				
t <sub>PHL</sub>	Maximum Propagation		18	27	ns
	Delay, Clear to Output				
t <sub>REM</sub>	Minimum Removal Time,		10	20	ns
	Clear to Clock				
t <sub>s</sub>	Minimum Setup Time		10	20	ns
	Data to Clock				
t <sub>H</sub>	Minimum Hold Time		-2	0	ns
	Clock to Data				
t <sub>W</sub>	Minimum Pulse Width		10	16	ns
	Clock or Clear				

### **AC Electrical Characteristics**

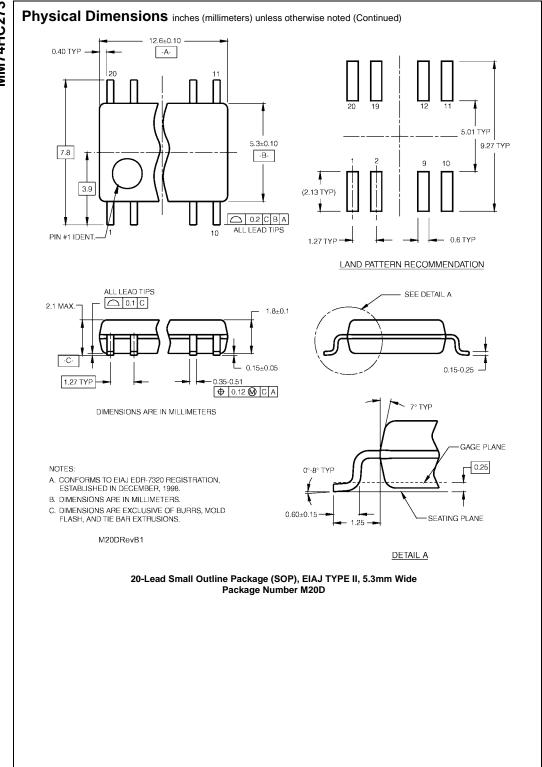
 $C_L = 50 \text{ pF}, t_f = t_f = 6 \text{ ns} \text{ (unless otherwise specified)}$ 

0	Parameter	Conditions	v <sub>cc</sub>	T <sub>A</sub> = 25°C		T <sub>A</sub> = -40 to 85°C T <sub>A</sub> = -55 to 125°C		Units
Symbol				Тур	Guaranteed Limits			
f <sub>MAX</sub>	Maximum Operating		2.0V	16	5	4	3	MHz
	Frequency		4.5V	74	27	21	18	MHz
			6.0V	78	31	24	20	MHz
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation		2.0V	38	135	170	205	ns
	Delay, Clock to Output		4.5V	14	27	34	41	ns
			6.0V	12	23	29	35	ns
t <sub>PHL</sub>	Maximum Propagation		2.0V	42	135	170	205	ns
	Delay, Clear to Output		4.5V	19	27	34	41	ns
			6.0V	18	23	29	35	ns
t <sub>REM</sub>	Minimum Removal Time		2.0V	0	25	32	37	ns
	Clear to Clock		4.5V	0	5	6	7	ns
			6.0V	0	4	5	6	ns
t <sub>s</sub>	Minimum Setup Time		2.0V	26	100	125	150	ns
	Data to Clock		4.5V	7	20	25	30	ns
			6.0V	5	17	21	25	ns
t <sub>H</sub>	Minimum Hold Time		2.0V	-15	0	0	0	ns
	Clock to Data		4.5V	-6	0	0	0	ns
			6.0V	-4	0	0	0	ns
t <sub>W</sub>	Minimum Pulse Width		2.0V	34	80	100	120	ns
	Clock or Clear		4.5V	11	16	20	24	ns
			6.0V	10	14	18	20	ns
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and		2.0V		1000	1000	1000	ns
	Fall Time, Clock		4.5V		500	500	500	ns
			6.0V		400	400	400	ns
t <sub>THL</sub> , t <sub>TLH</sub>	Maximum Output Rise		2.0V	28	75	95	110	ns
	and Fall Time		4.5V	11	15	19	22	ns
			6.0V	9	13	16	19	ns
C <sub>PD</sub>	Power Dissipation	(per flip-flop)		45				pF
	Capacitance (Note 5)							
C <sub>IN</sub>	Maximum Input			7	10	10	10	pF
	Capacitance							

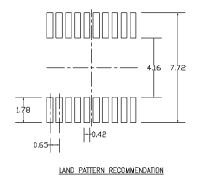
Note 5:  $C_{PD}$  determines the no load dynamic power consumption,  $P_D = C_{PD} \ V_{CC}^2 f + I_{CC} \ V_{CC}$ , and the no load dynamic current consumption,  $I_S = C_{PD} \ V_{CC} \ f + I_{CC}$ .

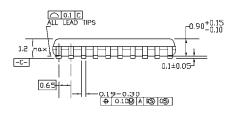


20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide Package Number M20B



# Physical Dimensions inches (millimeters) unless otherwise noted (Continued) -0.20 64 4.4±0.1 -B-







### DIMENSIONS ARE IN MILLIMETERS

### NOTES:

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- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

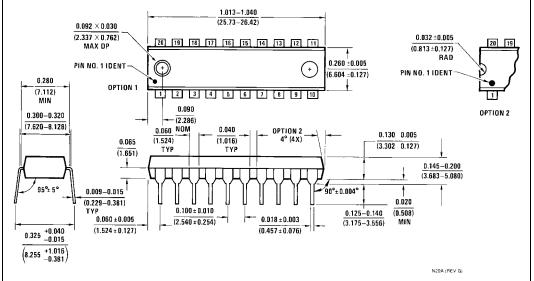
### <del>|</del>-12.00° R0.09mir GAGE PLANE 0.6±0.1 R0.09min -1.00 DETAIL A

### MTC20REVD1

PIN #1 IDENT.

20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC20

## Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N20A

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